MOSFETs Silicon N-Channel MOS (U-MOSVII-H)

# **TPCA8058-H**

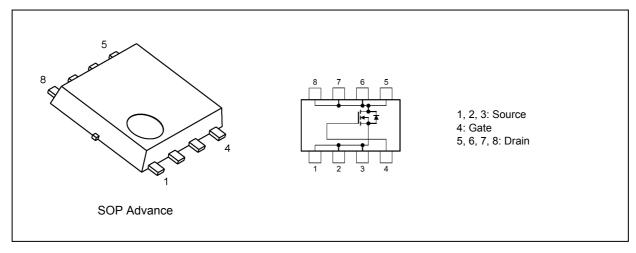
# 1. Applications

- High-Efficiency DC-DC Converters
- Notebook PCs
- Mobile Equipment

#### 2. Features

- (1) Small footprint due to a small and thin package
- (2) High-speed switching
- (3) Small gate charge:  $Q_{SW} = 12 \text{ nC}$  (typ.)
- (4) Low drain-source on-resistance:  $R_{DS(ON)} = 3.0 \text{ m}\Omega \text{ (typ.)} (V_{GS} = 4.5 \text{ V})$
- (5) Low leakage current:  $I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 30 \ V)$
- (6) Enhancement mode:  $V_{th}$  = 1.3 to 2.3 V ( $V_{DS}$  = 10 V,  $I_D$  = 0.5 mA)

### 3. Packaging and Internal Circuit



## 4. Absolute Maximum Ratings (Note) ( $T_a = 25$ °C unless otherwise specified)

Characteristics				Rating	Unit
Drain-source voltage			V <sub>DSS</sub>	30	V
Gate-source voltage			V <sub>GSS</sub>	±20	
Drain current (DC)		(Note 1)	Ι <sub>D</sub>	38	Α
Drain current (pulsed)		(Note 1)	I <sub>DP</sub>	114	7
Power dissipation	(T <sub>c</sub> = 25 °C)		PD	52	W
Power dissipation	(t = 10 s)	(Note 2)	PD	2.8	W
Power dissipation	(t = 10 s)	(Note 3)	PD	1.6	W
Single-pulse avalanche energy		(Note 4)	E <sub>AS</sub>	187	mJ
Avalanche current			I <sub>AR</sub>	38	Α
Channel temperature			T <sub>ch</sub>	150	°C
Storage temperature			T <sub>stg</sub>	-55 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 5. Thermal Characteristics

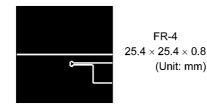
Characteristics				Max	Unit
Channel-to-case thermal resistance	(T <sub>c</sub> = 25 °C)		R <sub>th(ch-c)</sub>	2.4	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 2)	R <sub>th(ch-a)</sub>	44.6	
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 3)	R <sub>th(ch-a)</sub>	78.1	

Note 1: Ensure that the channel temperature does not exceed 150 °C.

Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 4: V\_DD = 24 V, T\_ch = 25 °C (initial), L = 0.1 mH, R\_G = 1  $\Omega$ , I<sub>AR</sub> = 38 A



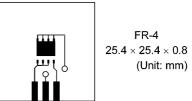
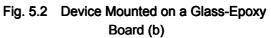


Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)



Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

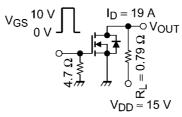
### 6. Electrical Characteristics

### 6.1. Static Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I <sub>GSS</sub>	$V_{GS}$ = ±20 V, $V_{DS}$ = 0 V	_		±0.1	μA
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V	_		10	
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	30		_	V
	V <sub>(BR)DSX</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = -20 V	15	_	_	
Gate threshold voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.5 mA	1.3		2.3	
Drain-source on-resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 19 A	_	3.0	3.8	mΩ
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 19 A	_	2.3	3.0	

# 6.2. Dynamic Characteristics ( $T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	3600	4300	pF
Reverse transfer capacitance	C <sub>rss</sub>		_	200	310	
Output capacitance	C <sub>oss</sub>			680	_	
Gate resistance	rg	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 5 MHz	_	1.4	2.1	Ω
Switching time (rise time)	t <sub>r</sub>	See Fig. 6.2.1.	_	4.3	_	ns
Switching time (turn-on time)	t <sub>on</sub>			13	_	
Switching time (fall time)	t <sub>f</sub>	]		6.9	_	
Switching time (turn-off time)	t <sub>off</sub>	]	_	48	—	



Duty  $\leq$  1%, t<sub>w</sub> = 10  $\mu$ s

Fig. 6.2.1 Switching Time Test Circuit

### 6.3. Gate Charge Characteristics ( $T_a = 25$ °C unless otherwise specified)

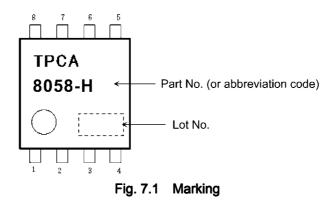
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus	Qg	$V_{DD}\approx 24~V,~V_{GS}\text{ = }10~V,~I_{D}\text{ = }38~A$	_	51	_	nC
gate-drain)		$V_{DD} \approx 24$ V, $V_{GS}$ = 5 V, $I_D$ = 38 A	_	26	—	
Gate-source charge 1	Q <sub>gs1</sub>	$V_{DD} \approx 24$ V, $V_{GS}$ = 10 V, $I_D$ = 38 A		11	_	
Gate-drain charge	Q <sub>gd</sub>		_	6.4	_	
Gate switch charge	Q <sub>SW</sub>		_	12	_	

### 6.4. Source-Drain Characteristics ( $T_a = 25$ °C unless otherwise specified)

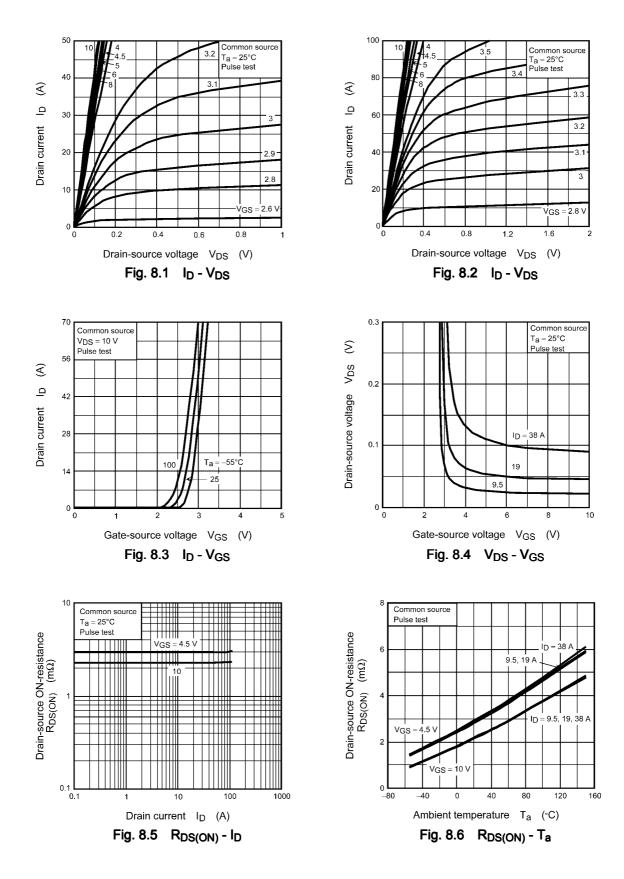
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed) (Not	e 5) I <sub>DRP</sub>	—	_	—	114	А
Diode forward voltage	V <sub>DSF</sub>	I <sub>DR</sub> = 38 A, V <sub>GS</sub> = 0 V			-1.2	V

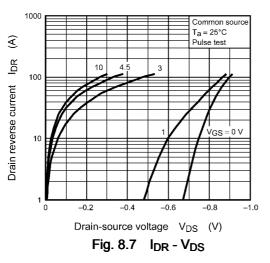
Note 5: Ensure that the channel temperature does not exceed 150 °C.

7. Marking



# 8. Characteristics Curves (Note)





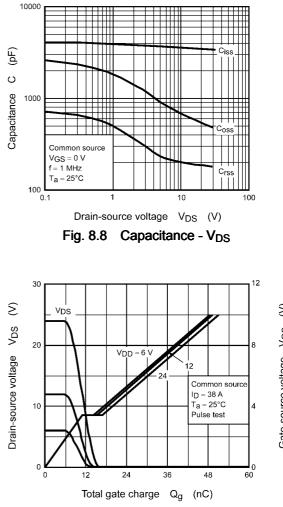
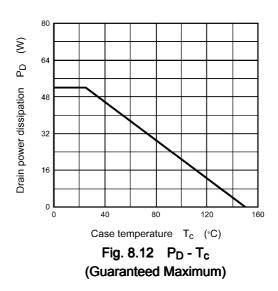
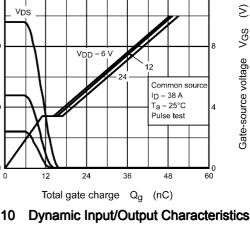
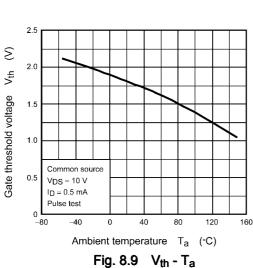
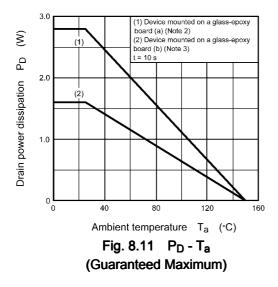


Fig. 8.10 Dynamic Input/Output Characteristics

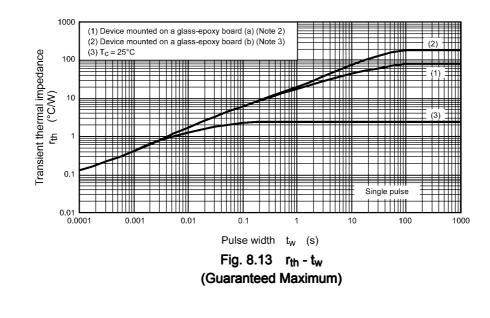


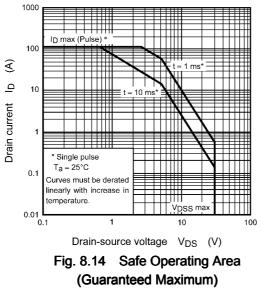










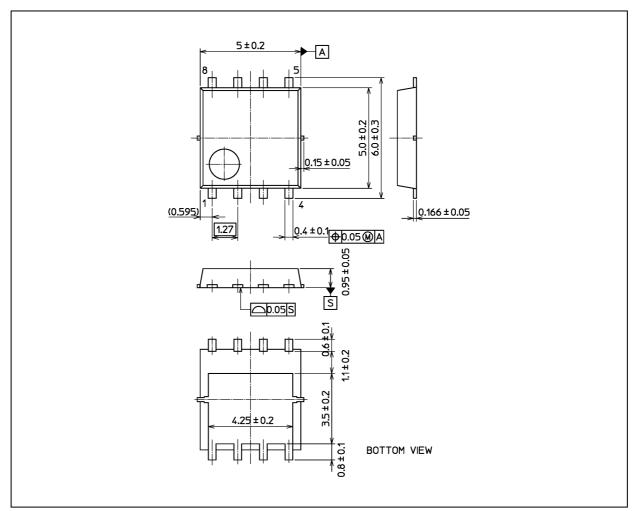


Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



# **Package Dimensions**

Unit: mm



Weight: 0.069 g (typ.)

TOSHIBA: 2-5Q1S

Nickname: SOP Advance

Package Name(s)

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